





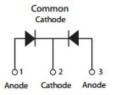
## **MBRF1060CTP SCHOTTKY RECTIFIER**



#### **Features**

- 150°C T<sub>J</sub> operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- · High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

#### **Circuit Diagram**



#### **Applications**

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

#### **Maximum Ratings:**

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	$V_{RRM}$	-		
Working Peak Reverse Voltage	$V_{RWM}$		60	V
DC Blocking Voltage	$V_{R}$			
Average Rectified Forward Current	I <sub>F (AV)</sub>	50% duty cycle @Tc=133°C, rectangular	5(Per Leg)	^
		wave form	10(Per Device)	А
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I <sub>FSM</sub>	8.3ms, Half Sine pulse	125	Α

#### **Electrical Characteristics:**

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop	V <sub>F1</sub>	@ 5A, Pulse, T <sub>J</sub> = 25 °C	0.66	0.70	V
(Per Leg)*	V <sub>F2</sub>	@ 5A, Pulse, T <sub>J</sub> = 125 °C	0.60	0.65	V
Reverse Current at DC condition	I <sub>R1</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 25 °C	0.009	1.0	mA
(Per Leg)*	I <sub>R2</sub>	@V <sub>R</sub> = rated V <sub>R</sub> , T <sub>J</sub> = 125 °C	3	15	mA
Junction Capacitance(Per Leg)	Ст	@V <sub>R</sub> = 5V, T <sub>C</sub> = 25 °C, f <sub>SIG</sub> = 1MHz		220	pF
Series Inductance(Per Leg)	Ls	Measured lead to lead 5 mm from package body		-	nH
Voltage Rate of Change	dv/dt	-		10,000	V/μs
RSM Isolation Voltage (t = 1.0 second, R. H. < =30%, T <sub>A</sub> = 25 °C)	V <sub>ISO</sub>	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	-	4500	V
·		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

<sup>\*</sup> Pulse width < 300 µs, duty cycle < 2%

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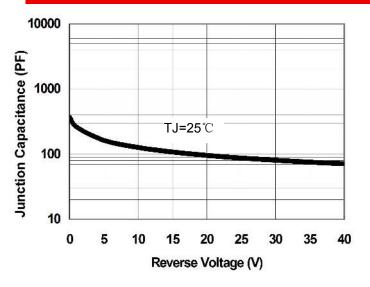




## **Thermal-Mechanical Specifications:**

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case	R <sub>θJC</sub>	DC operation	3.5	°C/W
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

## **Ratings and Characteristics Curves**



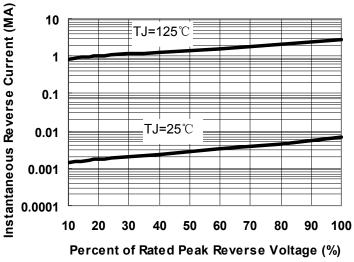


Fig.1-Typical Junction Capacitance

Fig.2-Typical Reverse Characteristics

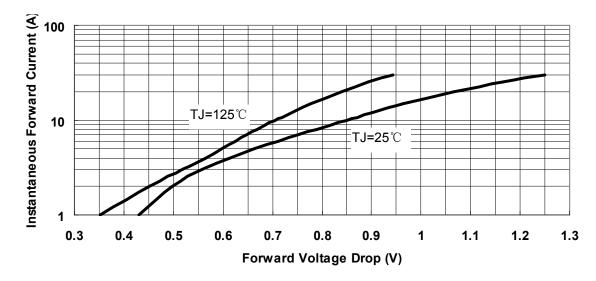


Fig.3-Typical Instantaneous Forward Voltage Characteristics

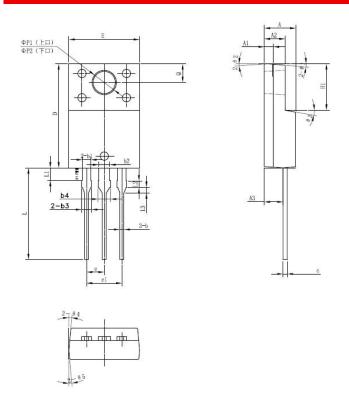
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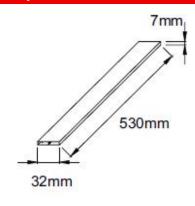


## **Mechanical Dimensions ITO-220AB**

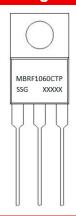


OVMBOL	Millimeters				
SYMBOL	MIN.	TYP.	MAX.		
Α	4.30	4.50	4.70		
A1	1.10	1.30	1.50		
A2	2.80	3.00	3.20		
A3	2.50	2.70	2.90		
b	0.50	0.60	0.75		
b1	1.10	1.20	1.35		
b2	1.50	1.60	1.75		
b3	1.20	1.30	1.45		
b4	1.60	1.70	1.85		
С	0.50	0.60	0.75		
D	14.80	15.00	15.20		
E	9.96	10.16	10.36		
е		2.55			
e1		5.10			
H1	6.50	6.70	6.90		
L	12.70	13.20	13.70		
L1	1.60	1.80	2.00		
L2	0.80	1.00	1.20		
L3	0.60	0.80	1.00		
<b>ΦΡ1</b> ( ├ □ )	3.30	3.50	3.70		
<b>ΦP2</b> (下口)	2.99	3.19	3.39		
Q	2.50	2.70	2.90		
Θ1		5°			
Θ2		4°			
Θ3		10°			
Θ4		5°			
Θ5		5°			

## **Tube Specification**



## **Marking Diagram**



Where XXXXX is YYWWL

 MBR
 = Device Type

 F
 = Package type

 10
 = Forward Current (10A)

 60
 = Reverse Voltage (60V)

 CTP
 = Configuration

 SSG
 = SSG

YY = Year WW = Week L = Lot Number

Cautions: Molding resin

Epoxy resin UL:94V-0

### **Ordering Information**

Device	Package	Shipping
MBRF1060CTP	ITO-220AB (Pb-Free)	50 pcs/ tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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